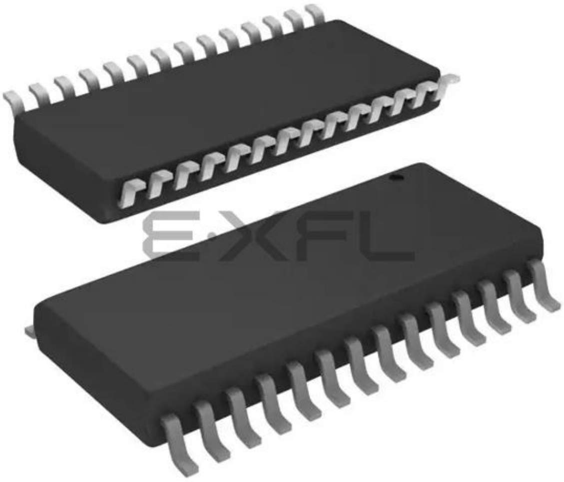
Microchip Technology - PIC16C62B-04/SO Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c62b-04-so

2.3 PCL and PCLATH

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 13 bits wide. The low byte is called the PCL register and is readable and writable. The high byte is called the PCH register. This register contains the PC<12:8> bits and is not directly accessible. All updates to the PCH register go through the PCLATH register.

2.3.1 STACK

The stack allows any combination of up to 8 program calls and interrupts to occur. The stack contains the return address from this branch in program execution.

Mid-range devices have an 8 level deep hardware stack. The stack space is not part of either program or data space and the stack pointer is not accessible. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN, RETLW` or a `RETFIE` instruction execution. PCLATH is not modified when the stack is PUSHed or POPed.

After the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

2.4 Program Memory Paging

The `CALL` and `GOTO` instructions provide 11 bits of address to allow branching within any 2K program memory page. When doing a `CALL` or `GOTO` instruction, the upper bit of the address is provided by PCLATH<3>. The user must ensure that the page select bit is programmed to address the proper program memory page. If a return from a `CALL` instruction (or interrupt) is executed, the entire 13-bit PC is popped from the stack. Therefore, manipulation of the PCLATH<3> bit is not required for the return instructions.

6.1 Timer2 Operation

The Timer2 output is also used by the CCP module to generate the PWM "On-Time", and the PWM period with a match with PR2.

The TMR2 register is readable and writable, and is cleared on any device reset.

The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The match output of TMR2 goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling) to generate a TMR2 interrupt (latched in flag bit TMR2IF, (PIR1<1>)).

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device reset (Power-on Reset, $\overline{\text{MCLR}}$ reset, Watchdog Timer reset or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

6.2 Timer2 Interrupt

The Timer2 module has an 8-bit period register PR2. Timer2 increments from 00h until it matches PR2 and then resets to 00h on the next increment cycle. PR2 is a readable and writable register. The PR2 register is initialized to FFh upon reset.

6.3 Output of TMR2

The output of TMR2 (before the postscaler) is fed to the Synchronous Serial Port module, which optionally uses it to generate shift clock.

TABLE 6-1 REGISTERS ASSOCIATED WITH TIMER2 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
0Ch	PIR1	—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	`-00- 0000`	`0000 0000`
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	`-0-- 0000`	`0000 0000`
11h	TMR2	Timer2 module's register								`0000 0000`	`0000 0000`
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	`-000 0000`	`-000 0000`
92h	PR2	Timer2 Period Register								`1111 1111`	`1111 1111`

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented read as '0'. Shaded cells are not used by the Timer2 module.

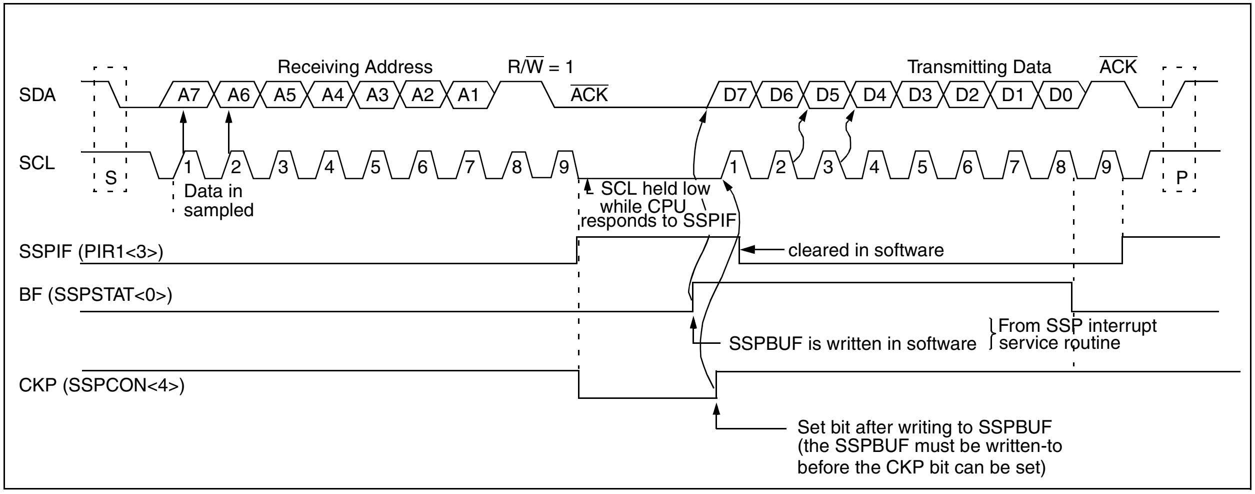
8.3.1.3 TRANSMISSION

When the R/$\overline{\text{W}}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{\text{W}}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{\text{ACK}}$ pulse will be sent on the ninth bit and the CKP will be cleared by hardware, holding SCL low. Slave devices cause the master to wait by holding the SCL line low. The transmit data is loaded into the SSPBUF register, which in turn loads the SSPSR register. When bit CKP (SSPCON<4>) is set, pin RC3/SCK/SCL releases SCL. When the SCL line goes high, the master may resume operating the SCL line and receiving data. The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 8-4).

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{\text{ACK}}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{\text{ACK}}$), then the data transfer is complete. When the $\overline{\text{ACK}}$ is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{\text{ACK}}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP.

FIGURE 8-4: I^{2}C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



9.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

Note: This section applies to the PIC16C72A only.

The analog-to-digital (A/D) converter module has five input channels.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has the feature of being able to operate while the device is in SLEEP mode. To operate in sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

Additional information on the A/D module is available in the PIC® MCU Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device reset forces all registers to their reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 9-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 9-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

REGISTER 9-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
`00` = FOSC/2
`01` = FOSC/8
`10` = FOSC/32
`11` = FRC (clock derived from an internal RC oscillator)

bit 5-3: **CHS2:CHS0**: Analog Channel Select bits
`000` = channel 0, (RA0/AN0)
`001` = channel 1, (RA1/AN1)
`010` = channel 2, (RA2/AN2)
`011` = channel 3, (RA3/AN3)
`100` = channel 4, (RA5/AN4)

bit 2: **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1
`1` = A/D conversion in progress (setting this bit starts the A/D conversion)
`0` = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Unimplemented**: Read as '0'

bit 0: **ADON**: A/D On bit
`1` = A/D converter module is operating
`0` = A/D converter module is shutoff and consumes no operating current

REGISTER 9-2: ADCON1 REGISTER (ADDRESS 9Fh)

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCFG2	PCFG1	PCFG0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-3: **Unimplemented:** Read as '0'

bit 2-0: **PCFG2:PCFG0**: A/D Port Configuration Control bits

PCFG2:PCFG0	RA0	RA1	RA2	RA5	RA3	VREF
`000`	A	A	A	A	A	VDD
`001`	A	A	A	A	VREF	RA3
`010`	A	A	A	A	A	VDD
`011`	A	A	A	A	VREF	RA3
`100`	A	A	D	D	A	VDD
`101`	A	A	D	D	VREF	RA3
`11x`	D	D	D	D	D	VDD

A = Analog input

D = Digital I/O

9.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 µs.

The A/D module can operate during sleep mode, but the RC oscillator must be selected as the A/D clock source prior to the `SLEEP` instruction.

Table 9-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

9.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

Note 2: Analog levels on any pin that is defined as a digital input (including the AN4:AN0 pins) may cause the input buffer to consume current that is out of the devices specification.

TABLE 9-1 TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Device Frequency			
Operation	**ADCS1:ADCS0**	**20 MHz**	**5 MHz**	**1.25 MHz**	**333.33 kHz**
2TOSC	`00`	100 ns(2)	400 ns(2)	1.6 µs	6 µs
8TOSC	`01`	400 ns(2)	1.6 µs	6.4 µs	24 µs(3)
32TOSC	`10`	1.6 µs	6.4 µs	25.6 µs(3)	96 µs(3)
RC(5)	`11`	2 - 6 µs(1,4)	2 - 6 µs(1,4)	2 - 6 µs(1,4)	2 - 6 µs(1)

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 µs.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

10.10.1 INT INTERRUPT

The external interrupt on RB0/INT pin is edge triggered: either rising, if bit INTEDG (OPTION_REG<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 10.13 for details on SLEEP mode.

10.10.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 4.0)

10.10.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 3.2)

10.11 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt, (i.e., W register and STATUS register). This will have to be implemented in software.

Example 10-1 stores and restores the W and STATUS registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Stores the PCLATH register.
d) Executes the interrupt service routine code (User-generated).
e) Restores the STATUS register (and bank select bit).
f) Restores the W and PCLATH registers.

EXAMPLE 10-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
MOVWF    W_TEMP           ;Copy W to TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
CLRF     STATUS           ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
:
:(ISR)
:
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                          ;(sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
```

13.1 DC Characteristics: PIC16C62B/72A-04 (Commercial, Industrial, Extended) PIC16C62B/72A-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤+125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.0	-	5.5	V	XT, RC and LP osc mode
D001A			4.5	-	5.5	V	HS osc mode
			VBOR*	-	5.5	V	BOR enabled (Note 7)
D002*	VDR	RAM Data Retention **Voltage** (Note 1)	-	1.5	-	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	-	VSS	-	V	See section on Power-on Reset for details
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	-	-	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear)
D004A*			TBD	-	-		PWRT disabled ($\overline{\text{PWRTE}}$ bit set) See section on Power-on Reset for details
D005	VBOR	Brown-out Reset voltage trip point	3.65	-	4.35	V	BODEN bit set
D010	IDD	**Supply Current** (Note 2, 5)	-	2.7	5	mA	XT, RC osc modes FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	mA	HS osc mode FOSC = 20 MHz, VDD = 5.5V
D020	IPD	**Power-down Current** (Note 3, 5)	-	10.5	42	µA	VDD = 4.0V, WDT enabled,-40°C to +85°C
			-	1.5	16	µA	VDD = 4.0V, WDT disabled, 0°C to +70°C
D021			-	1.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +85°C
D021B			-	2.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +125°C
		Module Differential Current (Note 6)					
D022*	ΔIWDT	Watchdog Timer	-	6.0	20	µA	WDTE BIT SET, VDD = 4.0V
D022A*	ΔIBOR	Brown-out Reset	-	TBD	200	µA	BODEN bit set, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
$\overline{\text{OSC1}}$ = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc mode, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will perform a brown-out reset when VDD falls below VBOR.

13.4 AC (Timing) Characteristics

13.4.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS	3. TCC:ST	(I^{2}C specifications only)
2. TppS	4. Ts	(I^{2}C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$

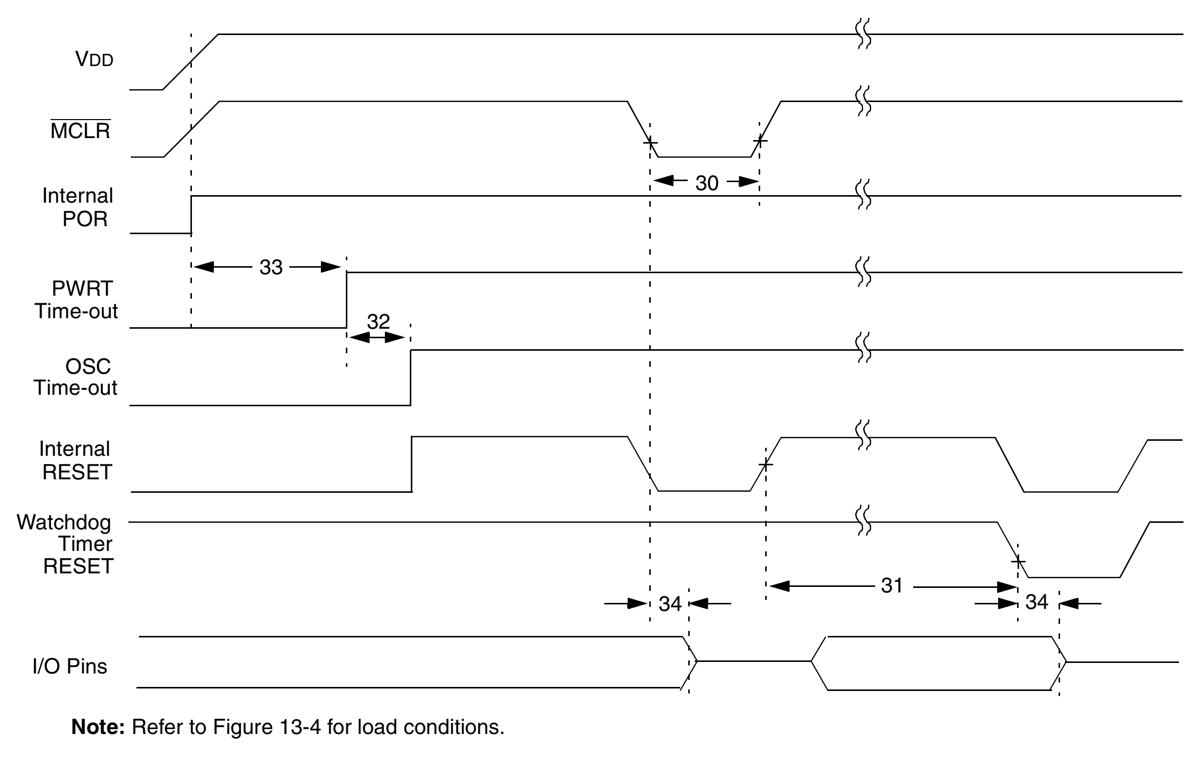
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I^{2}C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I^{2}C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

FIGURE 13-7: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 13-4 for load conditions.

FIGURE 13-8: BROWN-OUT RESET TIMING

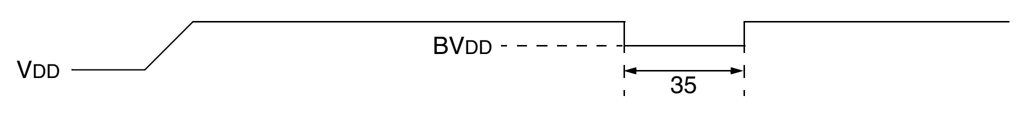


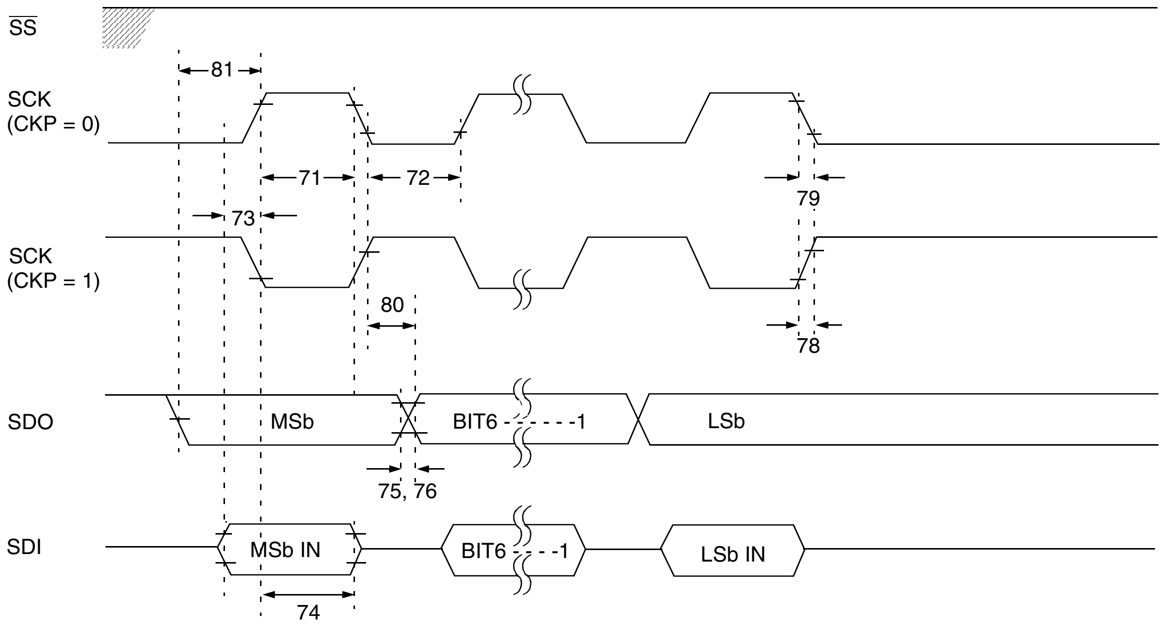
TABLE 13-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillator Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or WDT reset	—	—	2.1	µs	
35	TBOR	Brown-out Reset Pulse Width	100	—	—	µs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-12: EXAMPLE SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 13-4 for load conditions.

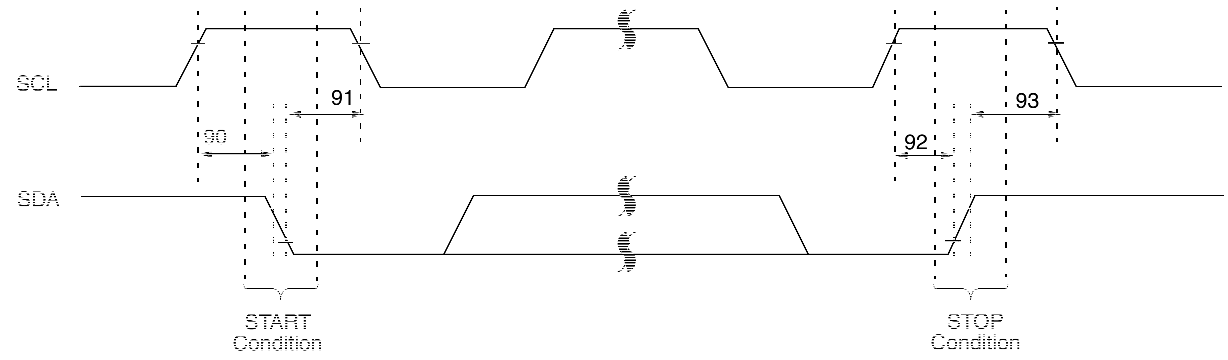
TABLE 13-8: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
71	TscH	SCK input high time (slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A			Single Byte	40	—	—	ns	Note 1
72	TscL	SCK input low time (slave mode)	Continuous	1.25TCY + 30	—	—	ns	
72A			Single Byte	40	—	—	ns	Note 1
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	Note 1
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75	TdoR	SDO data output rise time	**PIC16CXX**	—	10	25	ns	
			PIC16LCXX		20	45	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
78	TscR	SCK output rise time (master mode)	**PIC16CXX**	—	10	25	ns	
			PIC16LCXX		20	45	ns	
79	TscF	SCK output fall time (master mode)		—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	**PIC16CXX**	—	—	50	ns	
			PIC16LCXX		—	100	ns	
81	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		TCY	—	—	ns	

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.

FIGURE 13-15: I^{2}C BUS START/STOP BITS TIMING



Note: Refer to Figure 13-4 for load conditions.

TABLE 13-11: I^{2}C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90*	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
		Setup time	400 kHz mode	600	—	—		
91*	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
		Hold time	400 kHz mode	600	—	—		
92*	TSU:STO	STOP condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

TABLE 13-13: A/D CONVERTER CHARACTERISTICS: PIC16C72A-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C72A-20 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16LC72A-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	8-bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Total Absolute error		—	—	< ± 1	LSB	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error		—	—	< ± 1	LSB	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error		—	—	< ± 1	LSB	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A05	EFS	Full scale error		—	—	< ± 1	LSB	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error		—	—	< ± 1	LSB	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity		—	guaranteed (Note 3)	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage		2.5V	—	VDD + 0.3	V	
A25	VAIN	Analog input voltage		VSS - 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	**PIC16CXX**	—	180	—	µA	Average current consumption when A/D is on. (Note 1)
			PIC16LCXX	—	90	—	µA	
A50	IREF	VREF input current (Note 2)		10	—	1000	µA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1.
				—	—	10	µA	During A/D conversion cycle

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage and has no missing codes.

14.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for **design guidance** and are **not tested**.

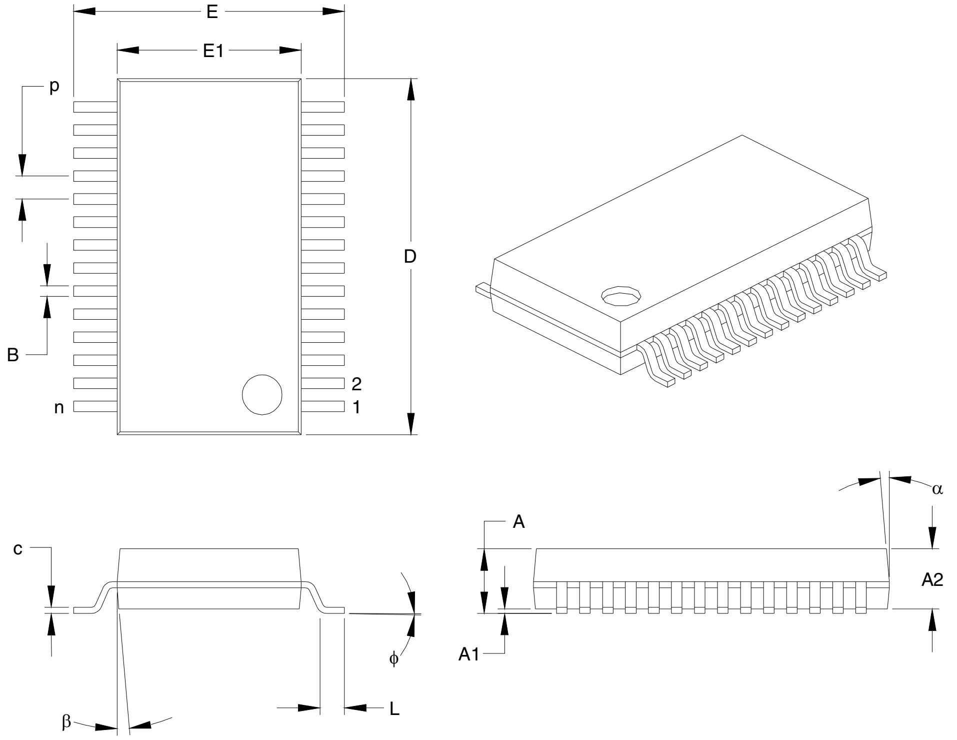
In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are guaranteed to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C. 'Max' or 'min' represents (mean + 3σ) or (mean - 3σ) respectively, where σ is standard deviation, over the whole temperature range.

Graphs and Tables not available at this time.

Data is not available at this time but you may reference the *PIC16C72 Series Data Sheet* (DS39016,) DC and AC characteristic section, which contains data similar to what is expected.

15.5 28-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.026			0.66	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.319	7.59	7.85	8.10
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.396	.402	.407	10.06	10.20	10.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-150

Drawing No. C04-073

NOTES:

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